

L Number	Hits	Search Text	DB	Time stamp
1	36457	plasma adj3 etch\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/01 10:48
2	12327	(plasma adj3 etch\$) and dielectric	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/01 10:48
9	4774	((plasma adj3 etch\$) and dielectric) and pressure and power	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/01 10:49
16	1018	((plasma adj3 etch\$) and dielectric) and pressure and power) and chlorine	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/01 10:50
23	532	((plasma adj3 etch\$) and dielectric) and pressure and power) and chlorine) and carbon	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/01 10:50
30	133	((plasma adj3 etch\$) and dielectric) and pressure and power) and chlorine) and carbon) and sulfur	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/01 10:57
37	91	((plasma adj3 etch\$) and dielectric) and pressure and power) and hafnium	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/01 11:10
44	203	((plasma adj3 etch\$) and dielectric) and pressure and power) and (carbon adj monoxide)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/01 11:11
51	103	((plasma adj3 etch\$) and dielectric) and pressure and power) and (carbon adj monoxide) and chlorine	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/01 11:22
58	271	((plasma adj3 etch\$) and dielectric) and pressure and power) and ferroelectric	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/01 11:23
65	55	((plasma adj3 etch\$) and dielectric) and pressure and power) and ferroelectric) and halogen	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/11/01 11:23